

PRODUCT NUMBER

10056845-YXXYLF

PLATING

- 1- 0.76µm GOLD/GXT (PdNi WITH GOLD FLASH) ON CONTACT AREA
- 2µm MIN MATTE TIN ON TAILS.
- 1.27µm NICKEL MIN UNDERPLATING

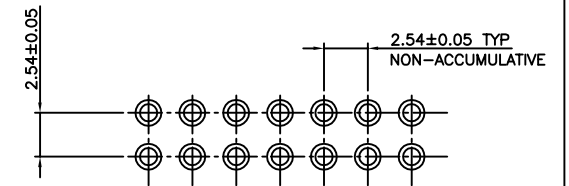
LEAD FREE, RoHS COMPATIBLE, NOTE 8.

PACKAGING NOTE 5

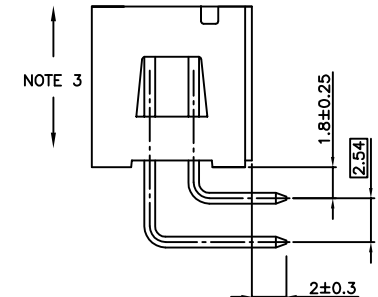
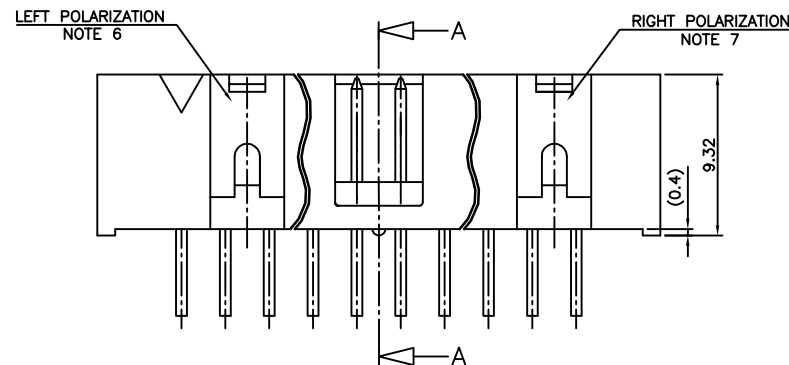
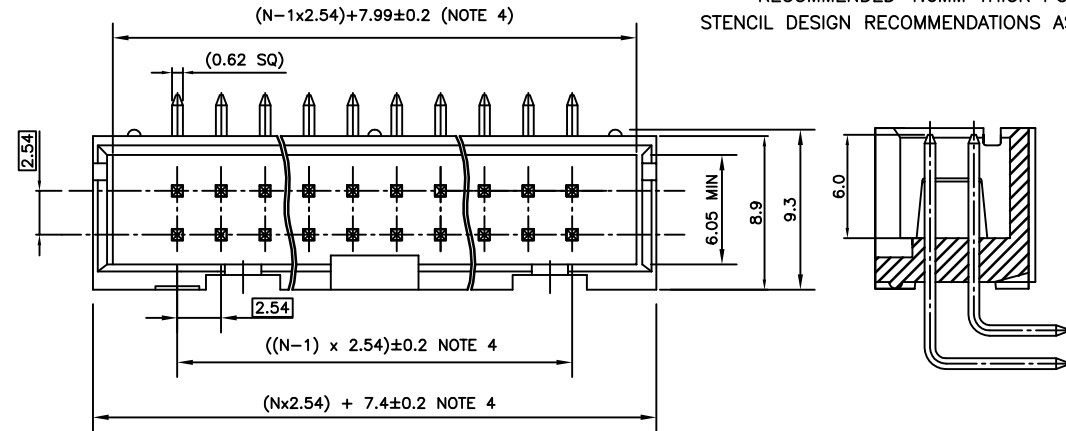
STYLE	SIZE
06	2x03
08	2x04
10	2x05
14	2x07
16	2x08
20	2x10
26	2x13
30	2x15
34	2x17
40	2x20

NOTES:

- HOUSING MATERIAL: HIGH TEMPERATURE THERMOPLASTIC, UL94 V-0 COLOR BLACK.
- CONTACT MATERIAL: COPPER ALLOY
- MINIMUM PUSH OUT FORCE OF PIN IN EITHER DIRECTION : 20N BEFORE SOLDERING.
- TO DETERMINE DIMENSIONS :
N = NUMBER OF POSITIONS PER ROW
EXAMPLE : 8 POS N x 2.54 = 20.32mm
- PACKAGING:
OMMIT = STANDARD TUBE PACKAGING.
K = TAPE AND REEL PACKAGING WITHOUT CAP ON REQUEST.
- NO LEFT POLARIZATION ON STYLE 06, 08, 10, 14.
- NO RIGHT POLARIZATION ON STYLE 06, 08.
- RoHS COMPLIANT & COMPATIBLE PRODUCT SPECIFICATIONS
 - PLATING:
 - "LF" MEANS THE PRODUCT IS LEAD-FREE AND RoHS COMPLIANT
2µm MINIMUM MATTE TIN ON TAILS OVER 1.27µm MINIMUM NICKEL UNDERPLATE.
 - THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS PER GS-22-008.
 - MANUFACTURING PROCESS COMPATIBILITY
 - THE HOUSING WILL WITHSTAND EXPOSURE TO 260° PEAK TEMPERATURE FOR 10-30 SECONDS IN A CONVECTION INFRA-RED OR VAPOR PHASE REFLOW OVEN.



RECOMMENDED 1.6MM THICK PCB LAYOUT,
STENCIL DESIGN RECOMMENDATIONS AS PER TA-894



mat'l. code NOTES 1, 2				surface ISO 1302	tolerance ISO 406 ISO 1101	projection mm	product family QKIE HDR	
ltr	ecn no	dr	date	tolerances unless otherwise specified		mm	title	
A	F06-0280	LMU	06.09.19	angles	.x ± 0.3		QKIE HEADER	
B	F06-0335	LMU	06.12.08	linear	.xx ± 0.15	scale 1:1	LOW PROFILE PIN IN PASTE	
C	F07-0198	LMU	07.05.30		xxx ± 0.05		dwg no	
D	F08-0146	YOV	08.04.11	dr	L.MULIN 06.07.03	FCI	sheet 1 of 1 size	
E	F12-0089	JCO	12.07.23	engr	J.COMPAGNON 06.07.03		10056845 A3	
				chr			type CUSTOMER Drawing	
sheet index	revision sheet			appd	JM.C 06.09.19			